



Material Content Data Sheet



Sales Product Name	IPD60R400CE			Issued	25. January 2018			
MA#	MA001690336							
Package	PG-TO252-3-344			Weight*	323.92 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.522	1.40	1.40	13961	13961
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		133	
	non noble metal	iron	7439-89-6	0.144	0.04		445	
	non noble metal	copper	7440-50-8	143.904	44.43	44.48	444265	444843
	non noble metal	aluminium	7429-90-5	0.445	0.14	0.14	1375	1375
wire	non noble metal	aluminium	7429-90-5	0.445	0.14	0.14	1375	1375
encapsulation	organic material	carbon black	1333-86-4	0.671	0.21		2073	
	plastics	epoxy resin	-	18.129	5.60		55969	
	inorganic material	silicondioxide	60676-86-0	115.489	35.65	41.46	356541	414583
leadfinish	non noble metal	tin	7440-31-5	3.834	1.18	1.18	11835	11835
solder	non noble metal	tin	7440-31-5	0.074	0.02		228	
	noble metal	silver	7440-22-4	0.092	0.03		285	
	non noble metal	lead	7439-92-1	3.529	1.09	1.14	10895	11408
heatspreader	inorganic material	phosphorus	7723-14-0	0.010	0.00		31	
	non noble metal	iron	7439-89-6	0.033	0.01		102	
	non noble metal	copper	7440-50-8	32.995	10.19	10.20	101862	101995
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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